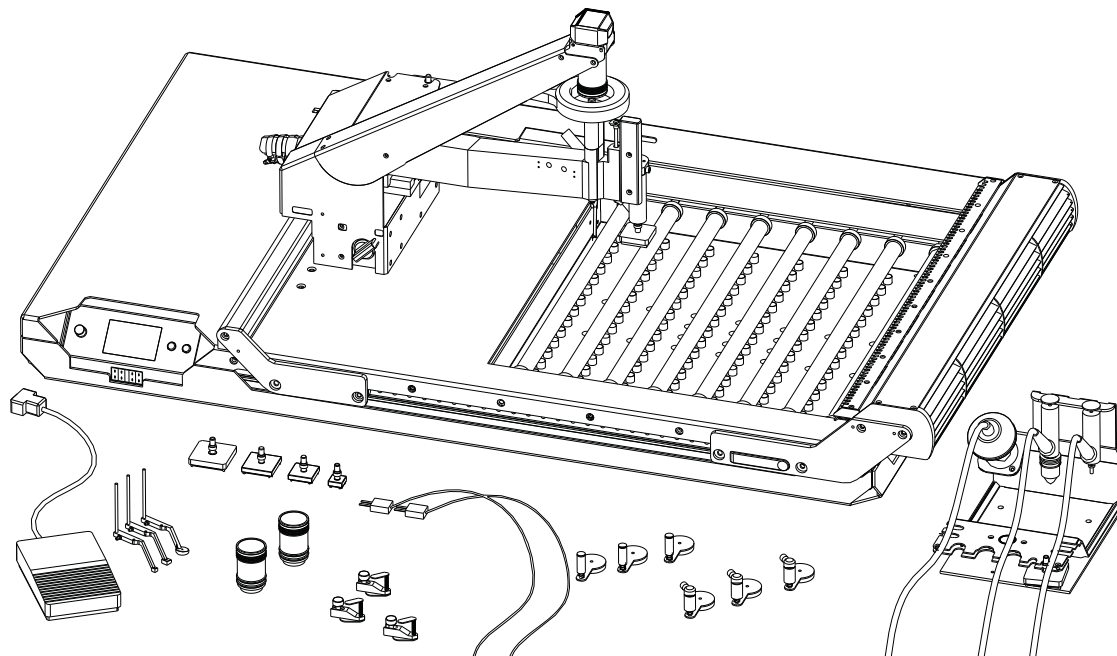


Rework Technic – EXPERT 10.6-HXV


Rework Station with 5000W Hybrid Underheater for PCBs up to 420x450mm². Heating area is analogues to PCB size adjustable. Automated SMD placement process by Auto Vision Placer (AVP) incl. Easy Solder software package and DBL 06 control unit with six high resolution sensors inputs for thermocouples (Type K).

This system is particularly suitable for large size PCBs like PCs, Laptops and Server Boards with small up to very big components.

Standard Equipment (Art.No. DB00.1066)

- Tool set for dispensing, placing, residual solder removal and soldering with magazine
- Set of placement nozzles XL-type (BGA/CSP) 5mm, 8mm, 15mm with O-Ring
- Set of solder nozzles (BGA) 15mm, 27mm, 35mm, 40mm
- Two camera lenses (BGA und CSP)
- Two thermo couple sensors (type K)
- Six PCB magnet holders 40,5mm (3 x standard, 3 x Easy Lock)
- Three PCB clips to install at hand rest
- Foot switch
- Rework ABC and manual




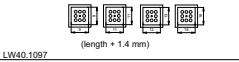
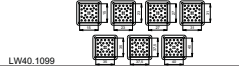
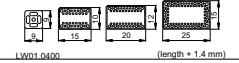
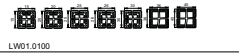

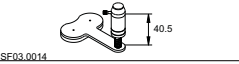
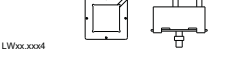



Technical Data

System power consumption:	5500 VA	
Power solder pen:	300 W, 35 l/min	
Power underheater:	1200 - 5000 W, 8 x IR lamps	
Effective heating area:	420 x 450 mm ²	
Max. PCB size:	490 x 600 mm ²	
Resolution motion system:	0,001 mm	
Placement accuracy :	± 0,015 mm	(Flip Chip)*
	± 0,030 mm	(CSP)
	± 0,040 mm	(BGA)
	± 0,070 mm	(Maxi BGA)*
High resolution CMOS-camera:	5 Mio. Pixel, USB2	
Camera field of view (FOV):	16 x 22 mm ²	(Flip Chip)*
	32 x 42 mm ²	(CSP)
	42 x 57 mm ²	(BGA)
	71 x 96 mm ²	(Maxi BGA)*
Mains:	1 Phase, 230VAC, Fuse 25A	
	Connector Type CEE 32A (3 phase)	
Pressurized air:	5 - 8 bar, 100l/min	
	clean dry air	
Foot print:	630 x 1030 mm ²	

*Optional Extras

Rework Technic – EXPERT 10.6-HXV

Optional Extras

SF66.0002	Micro SMD nozzles and lens for AVP 4XL licence MS, 3 n, 3 solder n, lens FC		1 piece
DVSX.0007	Report with pcb identification for ES 05, licence RP		1 piece
SF66.0110	Lens Maxi BGA for AVP4/4XL, f=16mm, 65*85mm		1 piece
LW40.1097	Soldering nozzle set CSP/QFN (lead free)* for all CSP types, 4 pieces (9, 11, 13, 16)		1 piece
LW40.1099	Solder nozzle set BGA 7 for all (98%) types of BGA, 7 pieces		1 piece
LW01.0400	Soldering tool set SO (lead free)* for all SO...SOL...TSOP, 4 pieces		1 piece
LW01.0100	Soldering tool set QFP for all PLCC ...QFP, 7 pieces		1 piece
SF36.1002	PCB flex support 40.5 for HIF 09, "12 pin"		1 piece
SF03.0014	PCB magnet holder Easy Lock 40.5 (snap) for IR/IRD/IRH/IRF radiation element		1 piece
LWxx.xxx4	Reballing oven and masks for all types of BGA/CSP, your choice		1 piece
SF71.0001	Side Camera for ES 05, camera, stand, cable, DVD		1 piece
DB00.0025	Nitrogen input for DBL 04/05/06 (2.p.r) reduces consumption of N2 for vacuum		1 piece
SF00.0028	Socket CEE 32 A for HIF 08/09 / IRF 07 with hints		1 piece